

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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MULTI-BEAM CARD EDGE CONNECTORS

TE Connectivity's (TE) next generation MULTI-BEAM card edge connectors deliver the best overall power and signal density to address server market requirements for performance, profile and cost. MULTI-BEAM card edge connectors are also applicable in global data communication applications to decrease costs.

These products are the next generation card edge connectors over the current SEC-II power card edge products and deliver superior current and signal density with a unique design.

The scalable and modular features also support greater flexibility in configuration and PCB design.

KEY BENEFITS

- · High density
- Better connectivity tolerance
- Modular design
- Better performance

APPLICATIONS

- Data center
- Telecommunications
- · Industrial automation devices
- Power systems

PRODUCT FEATURES & BENEFITS

High Density

- Highest signal density in the market with 60% signal space savings
- 30% power density improvement over legacy products
- Smaller pitch: signal pitch 1.00mm, power pitch 7.26mm
- Greater power contact, max. 43A

Better Connectivity Tolerance

- Better gatherability for blind-mate applications: +/-2.0mm (X), +/-1.54mm (Y)
- More clearance between PCB pads for signal contact to prevent solder bridging, and 1.3mm larger pads for easier alignment
- Support two PCB thickness: 1.57mm and 2.36mm

Modular Design

- Common power and signal contact module
- Flexible configuration with different contact quantities and positions
- Better scalability (AC & DC, low power & high power)

Better Performance

- Excellent mechanical and electrical performance
- Easy mating/un-mating with proper retention force
- · Low level contact resistance

PRODUCT CONFIGURATIONS



Vertical



Straddle



Right Angle

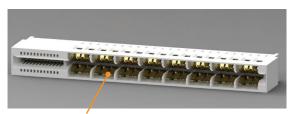
Dacitions

ORDERING INFORMATION

Positions		
Signal		
x4		
×24		
x12		
x4		
x5		
x4		
×24		
x4		
×24		
x6		
x6		



Signal - up to 60% space savings



Power - up to 30% space savings

Specifications

- Current rating:
 - Power contact: up to 43A
 - Signal contact: up to 2A
- Voltage rating:
 - Power: 100V max.
 - Signal: 60V max.
- Durability: 200 mating cycles
- Mechanical shock: EIA-364-27
- Vibration: EIA-364-28
- Operating temperature: -55°C to 105°C
- Low mating force
 - 6N max. per power contact
 - 1.5N max. per signal contact
- PCB thickness: 1.57mm and 2.36mm
- Material: high conductivity copper alloy and high temperature resin with RoHS compliance
- Product spec: 108-32043
- Application spec: 114-128016

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